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12-Bit Binary Counter

The MC14040B 12–stage binary counter is constructed with MOS P–Channel and N–Channel enhancement mode devices in a single monolithic structure. This part is designed with an input wave shaping circuit and 12 stages of ripple–carry binary counter. The device advances the count on the negative–going edge of the clock pulse. Applications include time delay circuits, counter controls, and frequency–driving circuits.

Features

- Fully Static Operation
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range
- Common Reset Line
- Pin-for-Pin Replacement for CD4040B
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	–0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	–65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Packages: -7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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SOIC-16 D SUFFIX CASE 751B

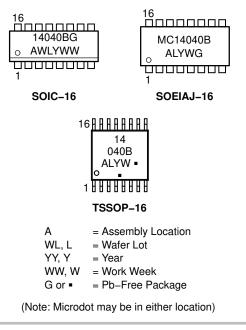
SOEIAJ-16 TS F SUFFIX D CASE 966 C/

rssop-16					
OT SUFFIX					
CASE 948F					

PIN ASSIGNMENT

Q12 [1•	16	
Q6 [2	15	Q11
Q5 [3	14	Q10
Q7 [4	13] Q8
Q4 [5	12] Q9
Q3 [6	11] R
Q2 [7	10	рс
v _{ss} [8	9	Q1

MARKING DIAGRAMS



ORDERING INFORMATION

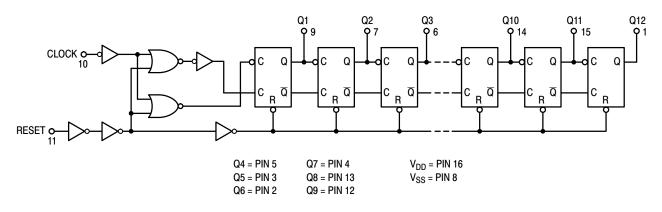
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

TRUTH TABLE

Clock	Reset	Output State
	0	No Change
\sim	0	Advance to next state
Х	1	All Outputs are low

X = Don't Care

LOGIC DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
MC14040BDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14040BDG*	SOIC-16 (Pb-Free)	48 Units / Rail
MC14040BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14040BDR2G*	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14040BDTR2G	TSSOP-16 (Pb-Free)	2500 Units / Tape & Reel
NLV14040BDTR2G*	TSSOP-16 (Pb-Free)	2500 Units / Tape & Reel
MC14040BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. *NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP

Capable.

ELECTRICAL CHARACTERISTICS	(Voltages Referenced to V _{SS})
----------------------------	---

				-55	5°C	25°C			125	5°C	
Characteristic		Symbol	V _{DD} Vdc	Min	Мах	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage $V_{in} = V_{DD}$ or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0 \text{ or } V_{DD}$	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- -	4.95 9.95 14.95		Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15	_ _ _	1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
$(V_{O} = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_{O} = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_{O} = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
$\begin{array}{l} \text{Output Drive Current} \\ (V_{OH} = 2.5 \text{ Vdc}) \\ (V_{OH} = 4.6 \text{ Vdc}) \\ (V_{OH} = 9.5 \text{ Vdc}) \\ (V_{OH} = 13.5 \text{ Vdc}) \end{array}$	Source	I _{OH}	5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	- - -	-2.4 -0.51 -1.3 -3.4	-4.2 -0.88 -2.25 -8.8		-1.7 -0.36 -0.9 -2.4		mAdc
$\begin{array}{l} (V_{OL} = 0.4 \; Vdc) \\ (V_{OL} = 0.5 \; Vdc) \\ (V_{OL} = 1.5 \; Vdc) \end{array}$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l _{in}	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance $(V_{in} = 0)$		C _{in}	_	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Note (Dynamic plus Quiesce Per Package) ($C_L = 50 \text{ pF}$ on all output buffers switching)	nt,	ΙŢ	5.0 10 15		<u>.</u>	I _T = (0	.42 μA/kHz) .85 μA/kHz) .43 μA/kHz)	f + I _{DD}	·	<u>.</u>	μAdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
3. The formulas given are for the typical characteristics only at 25°C.
4. To calculate total supply current at loads other than 50 pF:

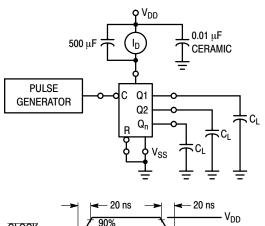
 $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$

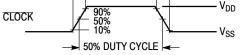
where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.001.

SWITCHING CHARACTERISTICS (Note 5) (C_L = 50 pF, T_A = 25° C)

Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time T_{TLH} , $T_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ T_{TLH} , $T_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ T_{TLH} , $T_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q1 $t_{PHL}, t_{PLH} = (1.7 \text{ ns/pF}) \text{ C}_L + 315 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.66 \text{ ns/pF}) \text{ C}_L + 137 \text{ ns}$ $t_{PHL}, t_{PLH} = (0.5 \text{ ns/pF}) \text{ C}_L + 95 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15	- - -	260 115 80	520 230 160	ns
Clock to Q12 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 2415 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 867 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 475 \text{ ns}$		5.0 10 15	- - -	1625 720 500	3250 1440 1000	ns
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 485 \text{ ns}$ $t_{PHL} = (0.86 \text{ ns/pF}) C_L + 182 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 145 \text{ ns}$	t _{PHL}	5.0 10 15	- - -	370 155 115	740 310 230	ns
Clock Pulse Width	twn	5.0 10 15	385 150 115	140 55 38		ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	- - -	2.1 7.0 10.0	1.5 3.5 4.5	MHz
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15		No Limit		ns
Reset Pulse Width	twn	5.0 10 15	960 360 270	320 120 80	_ _ _	ns
Reset Removal Time	t _{rem}	5.0 10 15	130 50 30	65 25 15	- - -	ns

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.







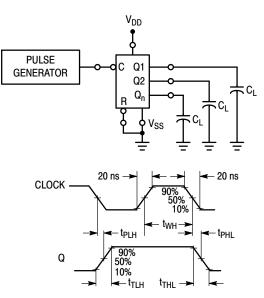
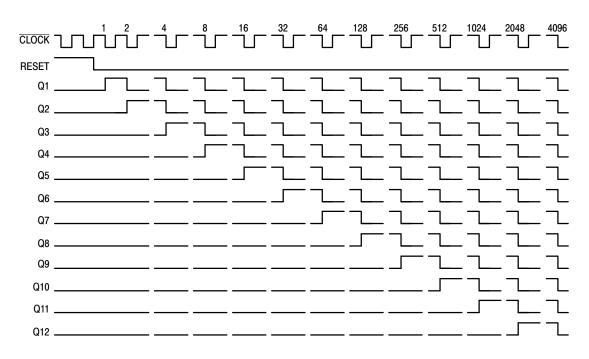


Figure 2. Switching Time Test Circuit and Waveforms





APPLICATIONS INFORMATION

TIME-BASE GENERATOR

A 60 Hz sinewave obtained through a 1.0 Megohm resistor connected directly to a standard 120 Vac power line is applied to the clock input of the MC14040B. By selecting

outputs Q5, Q10, Q11, and Q12 division by 3600 is accomplished. The MC14012B decodes the counter outputs, produces a single output pulse, and resets the binary counter. The resulting output frequency is 1.0 pulse/minute.

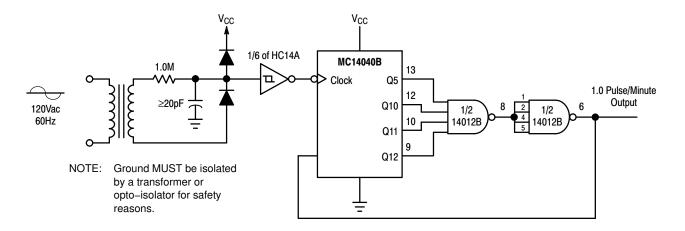
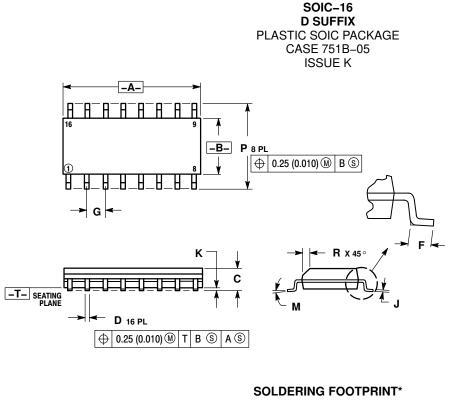
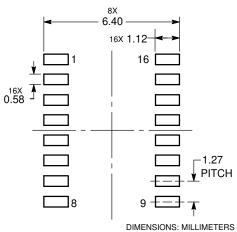


Figure 4. Time-Base Generator

PACKAGE DIMENSIONS





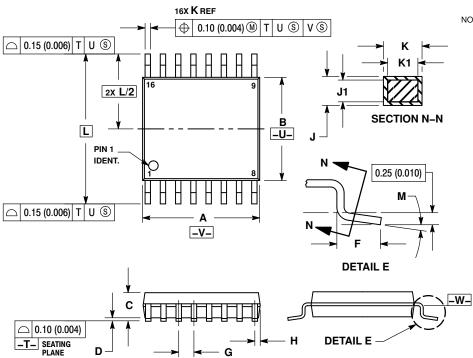
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD DODTOLISION
- PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 4. DIMENSION DI DOES NOT INCLUE DE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 5

	MILLIN	IETERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
Α	9.80	10.00	0.386	0.393			
В	3.80	4.00	0.150	0.157			
С	1.35	1.75	0.054	0.068			
D	0.35	0.49	0.014	0.019			
F	0.40	1.25	0.016	0.049			
G	1.27	BSC	0.050	BSC			
J	0.19	0.25	0.008	0.009			
Κ	0.10	0.25	0.004	0.009			
М	0 °	7°	0°	7°			
Р	5.80	6.20	0.229	0.244			
R	0.25	0.50	0.010	0.019			

PACKAGE DIMENSIONS

TSSOP-16 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948F ISSUE B



G

D

NOTES:

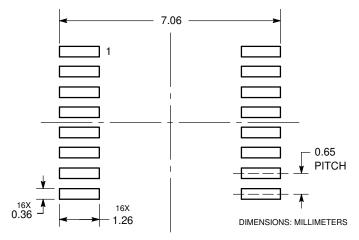
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ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. S. DIMENSION K DOES NOT INCLUDE 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE

DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
Κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40 BSC		0.252	BSC	
М	0 °	8 °	0 °	8 °	

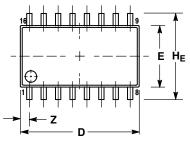
SOLDERING FOOTPRINT*

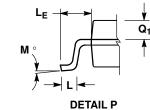


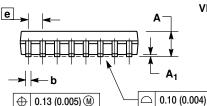
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

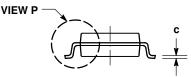
PACKAGE DIMENSIONS

SOEIAJ-16 F SUFFIX PLASTIC EIAJ SOIC PACKAGE CASE 966 ISSUE A









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER
- A DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH
- OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
С	0.10	0.20	0.007	0.011	
D	9.90	10.50	0.390	0.413	
E	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
Μ	0 °	10 °	0 °	10 °	
Q ₁	0.70	0.90	0.028	0.035	
Z		0.78		0.031	

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